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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3114052

SUBMISSION TYPE:	NEW ASSIGNMENT				
NATURE OF CONVEYANCE: ASSIGNMENT					
CONVEYING PARTY DATA					1

Name	Execution Date
KAI ZHU	11/19/2014
JIE CHEN	11/19/2014
WENJUN WENG	11/19/2014
SHANYUE MO	11/19/2014
ZHIGUANG GUO	11/19/2014

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANGJIANG ROAD, PUDONG NEW AREA
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14547319

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	00158.0199.00US
ATTORNET BOCKET NOMBER.	00100.0133.0000
NAME OF SUBMITTER:	MENG LIU
SIGNATURE:	/MENG LIU/
DATE SIGNED:	11/19/2014
This document serves as an Oath/Declaration (37 CFR 1.63).	

PATENT REEL: 034207 FRAME: 0809

Total Attachments: 3 source=Assignment001580199#page1.tif source=Assignment001580199#page2.tif source=Assignment001580199#page3.tif

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US Rights Page 1

ASSIGNMENT AND DECLARATION

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

High-Voltage-Tolerant Pull-Up Resistor Circuit

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on _______(Application No. ______); and

WHEREAS, <u>Semiconductor Manufacturing International (Shanghai) Corporation</u>, a corporation of <u>P. R. China</u> whose post office address is <u>18 Zhangliang Road</u>, <u>Pudong New Area</u>. <u>Shanghai, China</u> <u>201203</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application.

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No.______) filed ______) the filing date and application number of said application when known.

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US Rights

Further, as a below named inventor, I hereby declare that:

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filing data of the prior application and the national or PCT International filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1 Legal Name:	KAI ZHU			
Signature:	朱恺	Date:	2014.11	, t]
Inventor 2 Legal Name:	JIE CHEN			
Signature:	MA	Date:	2014.11	. 19
Inventor 3 Legal Name:	* • • WENJUN WENG			
Signature:	Jazz 7	Date:	Jay.11.1	<u>ĝ</u>

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form or must have been previously filed. Check the box below and complete the attached page(s) to list additional inventors.

X Additional inventors are being named on the <u>1</u> supplemental sheet(s) attached hereto.

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SUPPLEMENTAL DECLARATION A	. SHEET FOR AND ASSIGNMENT		TIONAL INVENTOR(emental Sheet Page	
Inventor 4 Legal Name:	SHANYUE MO			
Signature:	莫善岳	Date:	2014 . 11.19	
Inventor 5 Legal Name:	ZHIGUANG GUO		1	
Signature:	TPLA	Date:	21411	,19

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PATENT REEL: 034207 FRAME: 0813

RECORDED: 11/19/2014